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In re Application of:

Akram et al.

Serial No.: 09/241,177

Filed: February 1, 1999

For: HIGH DENSITY MODULARITY FOR
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Examiner: C. Novacek

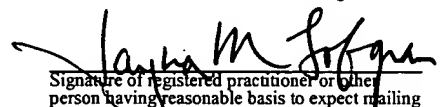
Group Art Unit: 2822

Attorney Docket No.: 3638US (98-0093)

CERTIFICATE OF MAILING

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AMENDMENT

Box NON-FEE AMENDMENT
Commissioner for Patents
Washington, D.C. 20231

Sir:

This amendment is in response to the Office Action of September 18, 2001 whose initial period of response is set to expire on December 18, 2001.